

That which is claimed is:

1. An energy-ray curing resin composition comprising a photopolymerizable resin component which can be cured by irradiation with an energy ray, a
5 photopolymerization initiator component which makes it possible to cure said photopolymerizable resin component with irradiation of an energy ray, and a curing agent component capable of curing at least one of said photopolymerizable resin components without
10 irradiation of an energy ray.

2. The energy-ray curing resin composition as described in claim 1, further comprising a curing
15 accelerator component which accelerates curing when curing at least one of said photopolymerizable resin components and said curing agent component without irradiation of an energy ray.

3. The energy-ray curing resin composition as described in claim 1 ~~or 2~~, comprising an epoxy resin component having a cyclic ether structure in a
20 molecular structure as the photopolymerizable resin component.

4. The energy-ray curing resin composition as described in ~~any of claims 1 to 3~~, comprising an acid anhydride or a derivative thereof as the curing agent
25 component.

5. The energy-ray curing resin composition as described in ~~any of claims 1 to 3~~, comprising monohydric or polyhydric alcohols as the curing agent component.

6. The energy-ray curing resin composition as described in claim 2 ~~or 3~~, comprising an acid anhydride or a derivative thereof and monohydric or polyhydric alcohols as the curing agent component or the curing accelerator component.

7. The energy-ray curing resin composition as described in ~~any of claims 3 to 6~~, wherein the curing agent component or the curing accelerator component comprises a compound which can react with the epoxy resin component and which does not have a nitrogen atom in a molecular structure.

8. The energy-ray curing resin composition as described in ~~any of claims 3 to 7~~, comprising 3,4-epoxycyclohexylmethyl-3,4-epoxycyclohexanecarboxylate as the photopolymerizable resin component.

9. The energy-ray curing resin composition as described in claim 4 ~~or any of claims 6 to 8~~, comprising maleic anhydride or a derivative thereof as the acid anhydride or derivative thereof.

10. The energy-ray curing resin composition as described in ~~any of claims 5 to 8~~, comprising

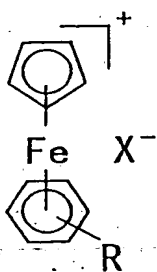
polyethylene glycol as the alcohols.

11. The energy-ray curing resin composition
as described in ~~any of claims 1 to 10~~, wherein the
curing agent component is present with a proportion
5 of 0.1 to 1.4 mol per mol of the photopolymerizable
resin component which can react with the curing agent
component.

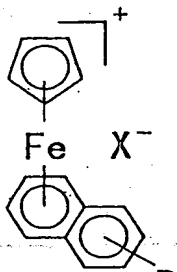
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12. The energy-ray curing resin composition
as described in claim 2, ~~3 or any of claims 6 to 11~~,
wherein the curing accelerator component is present
with a proportion of 0.04 to 0.6 mol per mol of the
curing agent component.

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13. The energy-ray curing resin composition
as described in ~~any of claims 1 to 12~~, comprising a
15 cationic photopolymerization initiator component as
the photopolymerization initiator component.

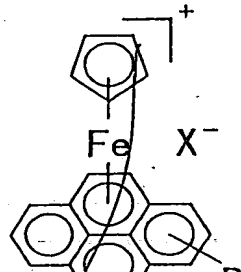
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14. The energy-ray curing resin composition
as described in ~~any of claims 1 to 13~~, comprising an
iron-allene base compound represented by the
20 following Formula (I), (II) or (III) as the
photopolymerization initiator component:



(I)



(II)



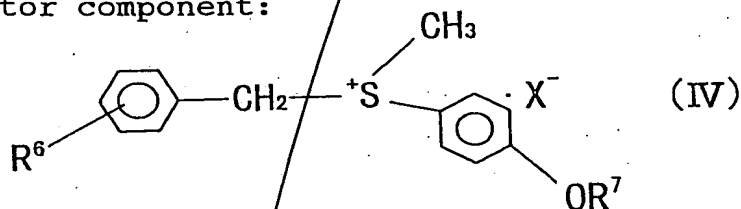
(III)

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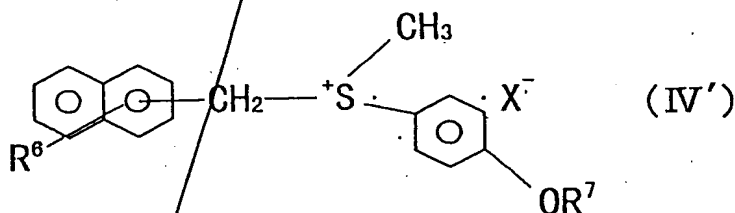
wherein X^- represents BF_4^- , PF_6^- , AsF_6^- or SbF_6^- .

15. The energy-ray curing resin composition as described in ~~any of claims 1 to 14~~, comprising a photo-thermopolymerization initiator which can initiate polymerization by both light and heat as the photopolymerization initiator component.

16. The energy-ray curing resin composition as described in ~~any of claims 1 to 15~~, comprising a sulfonium salt represented by the following Formula (IV), (IV') or (V) as the photopolymerization initiator component:



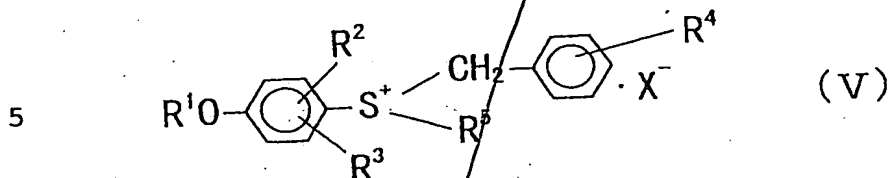
(IV)



(IV')

in Formula (IV) or (IV') described above, R^6

represents hydrogen, halogen, a nitro group or a methyl group; R^7 represents hydrogen, CH_3CO or CH_3OCO ; and X^- represents SbF_6^- , PF_6^- , AsF_6^- or BF_4^- ;



in Formula (V) described above, R^1 represents hydrogen, a methyl group, an acetyl group or a methoxycarbonyl group; R^2 and R^3 represent independently hydrogen, halogen or an alkyl group of C_1 to C_4 ; R^4 represents hydrogen, halogen or a methoxy group; R^5 represents an alkyl group of C_1 to C_4 ; and X^- represents SbF_6^- , PF_6^- , AsF_6^- or BF_4^- .

17. The energy-ray curing resin composition as described in ~~any of claims 1 to 16~~, wherein the photopolymerization initiator component comprises a photopolymerization initiator comprising a binary or higher system containing a photopolymerization initiator and a photo-thermopolymerization initiator.

20 18. The energy-ray curing resin composition as described in claim 17, wherein the polymerization initiator component comprising the binary or higher system contains at least one of aryl base sulfonium salts or the iron-allene base compounds represented by Formula (I), (II) or (III) as the

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photopolymerization initiator and at least one of the sulfonium salts represented by Formula (IV), (IV') or (V) as the photo-thermopolymerization initiator.

19. The energy-ray curing resin composition
5 as described in claim 17 ~~or 18~~, wherein the polymerization initiator component comprising the binary or higher system contains the photo-thermopolymerization initiator in a proportion of 10 to 100 % by weight.

10 20. The energy-ray curing resin composition
as described in ~~any of claims 1 to 19~~, wherein the photopolymerization initiator component is contained in a proportion of 0.1 to 6.0 parts by weight per 100 parts by weight of the total weight of the components
15 excluding the photopolymerization initiator component.

21. An energy-ray curing resin-molded article
obtained by curing the energy-ray curing resin
composition as described in ~~any of claims 1 to 20~~.

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22. A paste material comprising the energy-
20 ray curing resin composition as described in ~~any of claims 1 to 20~~.

23. A composite molding material comprising
the energy-ray curing resin composition as described
in ~~any of claims 1 to 20~~.

25 24. An adhesive comprising the energy-ray

curing resin composition as described in ~~any of~~
claims 1 ~~to 20~~.

25. A coating material comprising the energy-
ray curing resin composition as described in ~~any of~~
5 claims 1 ~~to 20~~.

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